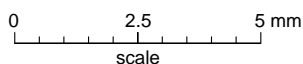
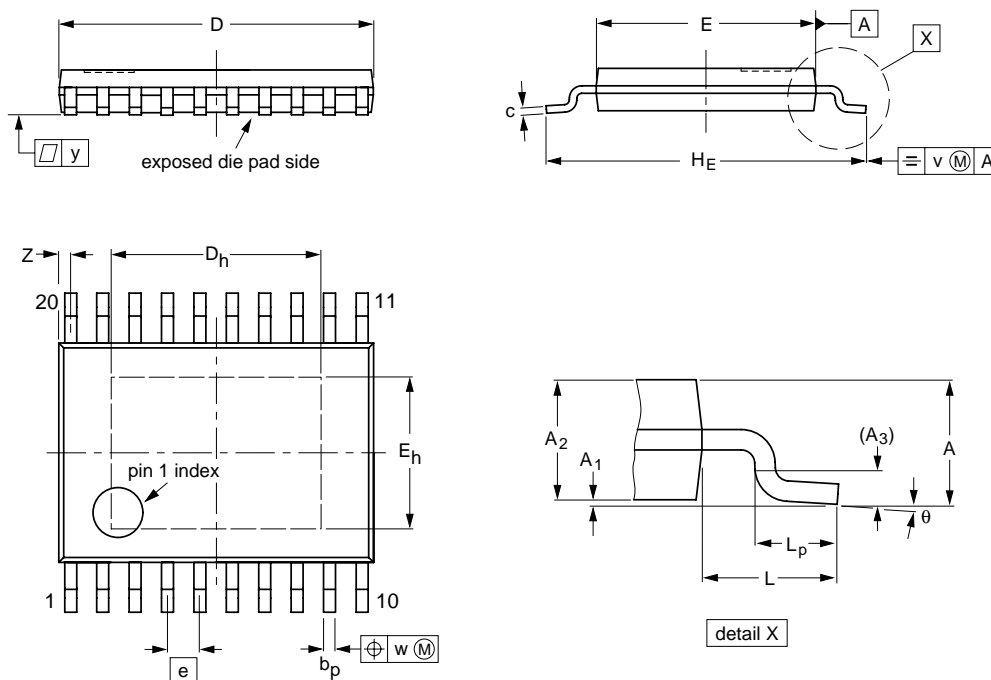


HTSSOP20: plastic thermal enhanced thin shrink small outline package; 20 leads;
body width 4.4 mm; exposed die pad

SOT527-1



DIMENSIONS (mm are the original dimensions)

| UNIT | A max. | A ₁ | A ₂ | A ₃ | b _p | c | D ⁽¹⁾ | D _h | E ⁽²⁾ | E _h | e | H _E | L | L _p | v | w | y | z ⁽¹⁾ | θ |
|------|--------|----------------|----------------|----------------|----------------|--------------|------------------|----------------|------------------|----------------|------|----------------|---|----------------|-----|------|-----|------------------|----------|
| mm | 1.1 | 0.15 0.05 | 0.95 0.80 | 0.25 | 0.30 0.19 | 0.20 0.09 | 6.6 6.4 | 4.3 4.1 | 4.5 4.3 | 3.1 2.9 | 0.65 | 6.6 6.2 | 1 | 0.75 0.50 | 0.2 | 0.13 | 0.1 | 0.5 0.2 | 8° 0° |

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|-------|-------|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | |
| SOT527-1 | | | | | 03-02-18 03-04-07 |